

**In the Claims:**

Please cancel claim 2, 6, 10, and 11 without prejudice.

Please amend claims 1, 3, 5, 7, 9, and 15 as follows:

1. (currently amended) A method for implementing multiple signals probing of a printed circuit board comprising the steps of:

providing a pattern of vias in the printed circuit board including multiple predefined vias, each said predefined via being connected to a respective signal to be monitored;

forming a probe structure on an outside surface of the printed circuit board including a pattern of a plurality of spaced apart electrically conductive stubs, each stub including an elongated portion extending from at least one pad, and said pattern including one of said plurality of stubs adjacent each said predefined via connected to said respective signal to be monitored;

electrically connecting a resistor with a between one said predefined via connected to one said respective signal to be monitored and said adjacent stub associated with a signal to be monitored; and

defining a path to a predefined probe location on the printed circuit board for monitoring said signal from said resistor using said probe structure by placing zero-ohm shorts between selected ones of said pads of said plurality of stubs of said probe structure.

2. (canceled)

3. (currently amended) A method for implementing multiple signals probing as recited in claim 2 wherein the step of forming said pattern of said plurality of stubs includes the step of etching an electrically conductive material in said pattern of said plurality of stubs to define said probe structure on said outside surface of the printed circuit board, ~~each stub including an elongated portion extending from at least one pad.~~

4. (original) A method for implementing multiple signals probing as recited in claim 3 wherein said electrically conductive material includes copper.

5. (currently amended) A method for implementing multiple signals probing as recited in claim 3 wherein the step of electrically connecting said resistor includes the step of placing said resistor between said predefined via ~~associated with said signal to be monitored~~ connected to one said respective signal to be monitored and said pad of an said adjacent one of said plurality of stubs of said probe structure.

6. (canceled)

7. (currently amended) A method for implementing multiple signals probing as recited in claim 1 wherein said resistor has a selected high resistance value relative to a characteristic impedance of the printed circuit board at said predefined via ~~associated with said signal to be monitored~~ connected to one said respective signal to be monitored.

8. (original) A method for implementing multiple signals probing as recited in claim 1 includes the steps of removing said resistor and said path after testing is completed.

9. (currently amended) Apparatus for implementing multiple signals probing of a printed circuit board comprising:

a pattern of vias in the printed circuit board including multiple predefined vias, each said predefined via being connected to a respective signal to be monitored;

a probe structure formed on an outside surface of the printed circuit board; said probe structure including an electrically conductive material forming a pattern of a plurality of spaced apart stubs defining said probe structure on said outside surface of the printed circuit board, each said stub including an elongated portion extending from at least one pad; said pattern including one of said plurality of stubs adjacent each said predefined via connected to said respective signal to be monitored;

a resistor electrically connected with a between one said predefined via connected to one said respective signal to be monitored and said adjacent stub  
~~associated with a signal to be monitored; and~~

a path defined to a predefined probe location for monitoring said signal from said resistor using said probe structure; said path being formed by electrically shorting between said pads of selected ones of said plurality of spaced apart stubs.

Claims 10-11 (canceled)

12. (original) Apparatus for implementing multiple signals probing as recited in claim 9 wherein said resistor and said path are removed after testing is completed.

13. (original) Apparatus for implementing multiple signals probing as recited in claim 9 wherein said probe structure formed on said outside surface of the printed

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circuit board includes an electrically conductive material etched to define a grid of a plurality of spaced apart stubs defining said probe structure.

14. (original) Apparatus for implementing multiple signals probing as recited in claim 13 wherein said electrically conductive material is copper.

15. (currently amended) Apparatus for implementing multiple signals probing as recited in claim 9 wherein said resistor has a selected high resistance value relative to a characteristic impedance of the printed circuit board at said predefined via ~~associated with said signal to be monitored~~ connected to one said respective signal to be monitored.